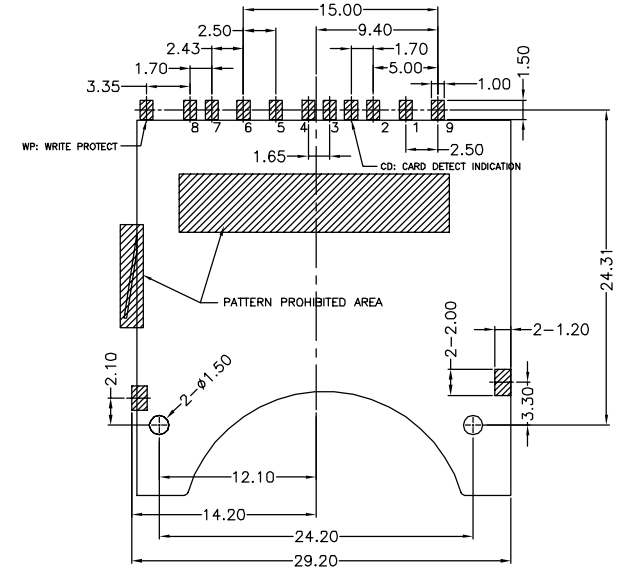
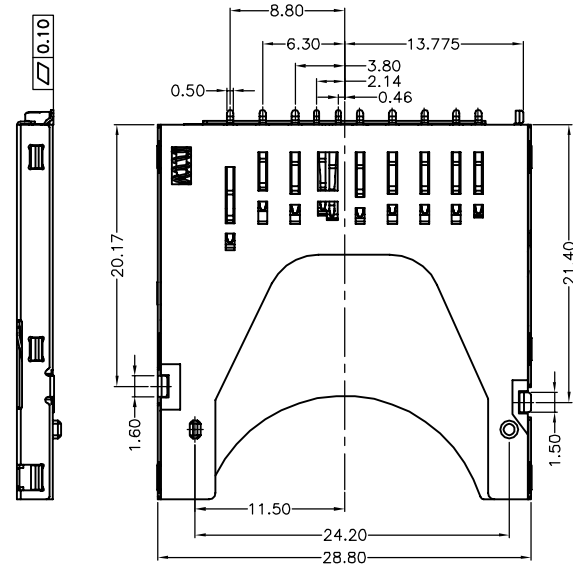
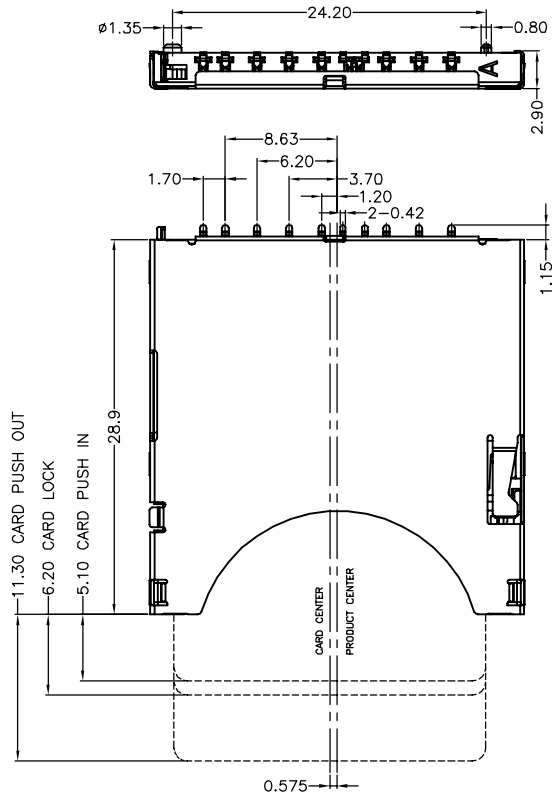


REV.	ECN. NO.	DESCRIPTION	ENG	DATE
A		ISSUED FROM X3	Jesse	03/13/12'
B		Modify Plating Spec.	Jesse	05/04/12'
C		Modify Plating Spec.	Jesse	07/18/13'



RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ±0.05)

Pin No.	SD	MMC
P1	MMC-DAT3 SD-CD/DAT3	1P 1P
P2	MMC-CMD SD-CMD	2P 2P
P3	MMC-VSS1 SD-VSS1	3P 3P
P4	MMC-VDD SD-VDD	4P 4P
P5	MMC-CLK SD-CLK	5P 5P
P6	MMC-VSS2 SD-VSS2	6P 6P
P7	MMC-DAT0 SD-DAT0	7P 7P
P8	SD-DAT1	8P
P9	SD-DAT2	9P

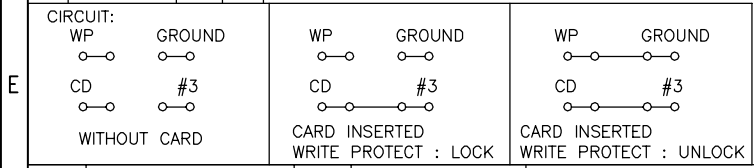
MATERIALS
 HOUSING: LCP+30%GF, UL94V-0, BLACK
 SHELL: STAINLESS STEEL SUS-304
 SOLDER PAD: STAINLESS STEEL SUS-304,
 1u" GOLD OVER 10u" NICKEL UNDER-PLATED
 SWITCH: PHOSPHOR BRONZE,
 GOLD PLATED ON CONTACT AREA
 100u" TIN PLATING ON SOLDER TAIL
 50u" NICKEL UNDER-PLATED
 TERMINAL: PHOSPHOR BRONZE,
 GOLD PLATED ON CONTACT AREA
 100u" TIN PLATING ON SOLDER TAIL
 50u" NICKEL UNDER-PLATED

SPECIFICATION
 CURRENT RATING: 0.5 AMP MAX
 OPERATING VOLTAGE: 3.3V
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 100m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 DURABILITY: 10000 CYCLES (DO NOT EXCHANGE CARDS)
 OPERATION TEMPERATURE: -25°C~+90°C
 RoHS COMPLIANCE

ORDER INFORMATION:

SDCR-2909-B K X 3 R 2N
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- CONNECTOR:
SDCR: SD CARD R/A CONNECTOR
- TYPE:
29: SD CARD PUSH-PUSH TYPE
- POSITIONS:
09: 9 POSITIONS
- INSULATOR MATERIAL:
B: LCP
- INSULATOR COLOR:
K: BLACK
- CONTACT AREA PLATING:
1=Gold Flash
3= 5u" Gold
4=10u" Gold
5=15u" Gold
6=30u" Gold
- SHIELD PLATING:
3: NICKEL PLATING
- PACKING:
R: TAPE & REEL



GENERAL TOLERANCE	ANGLE TOLERANCE	DRAWN	DATE	
X ± .X ± 0.38 .XX ± 0.25 .XXX ± 0.15	X° ± .X° ± .XX° ± .XXX° ±	Jesse	07/18/13'	
MATL SEE NOTES	FINISH SEE NOTES	CHECKED	DATE	PART NUMBER: SDCR-2909-BKX3R2N
SCALE N/A	UNIT mm	APPROVED	DATE	DRAWING NO. GT17-200114
SHEET 1 OF 2				SIZE A4 REV. C

ITEM	NAME	Q'TY	DESCRIPTION	MATERIAL	NOTE
1					